

# 1.5V Drive Pch MOSFET

#### RP1A090ZP

#### Structure

Silicon P-channel MOSFET

#### ● Features

- 1) Low Voltage Drive(1.5V drive).
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (MPT6).

#### Application

Switching

#### Packaging specifications

	Package	Taping	
Type	Code	TR	
	Basic ordering unit (pieces)	1000	
RP1A090Z	0		

#### ● Absolute maximum ratings (Ta = 25°C)

Param	Symbol	Limits	Unit	
Drain-source voltage		$V_{DSS}$	-12	V
Gate-source voltage		$V_{GSS}$	±10	V
Drain current	Continuous	I <sub>D</sub>	<u>+9</u>	Α
	Pulsed	I <sub>DP</sub> *1	±36	Α
Source current (Body Diode)	Continuous	I <sub>S</sub>	-1.6	Α
	Pulsed	I <sub>SP</sub> *1	-36	Α
Power dissipation		P <sub>D</sub> *2	2.0	W
Channel temperature		Tch	150	°C
Range of storage temperature		Tstg	-55 to +150	°C

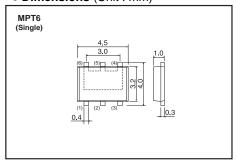
<sup>\*1</sup> Pw≤10μs, Duty cycle≤1%

#### • Thermal resistance

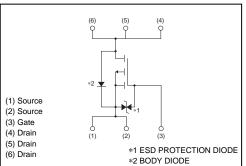
Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth (ch-a)*	62.5	°C/W

<sup>\*</sup>Mounted on a ceramic board.

#### Dimensions (Unit : mm)



#### • Inner circuit



<sup>\*2</sup> Mounted on a ceramic board.

#### ● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	1	-	±10	μA	$V_{GS}=\pm 10V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	-12	1	1	٧	I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	1	-1	μΑ	V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-0.3	1	-1.0	٧	$V_{DS}$ =-6V, $I_{D}$ =-1mA
	*	1	8	12	mΩ	$I_D = -9A$ , $V_{GS} = -4.5V$
Static drain-source on-state		1	11	16		I <sub>D</sub> =-4.5A, V <sub>GS</sub> =-2.5V
resistance	R <sub>DS (on)</sub>	1	15	23		I <sub>D</sub> =-4.5A, V <sub>GS</sub> =-1.8V
		-	19	38		I <sub>D</sub> =-1.8A, V <sub>GS</sub> =-1.5V
Forward transfer admittance	I Y <sub>fs</sub> I*	12	-	-	S	I <sub>D</sub> =-9A, V <sub>DS</sub> =-6V
Input capacitance	C <sub>iss</sub>	1	7400	-	рF	V <sub>DS</sub> =-6V
Output capacitance	C <sub>oss</sub>	1	800	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	750	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	35	-	ns	I <sub>D</sub> =-4.5A, V <sub>DD</sub> ≒-6V
Rise time	t <sub>r</sub> *	1	120	-	ns	V <sub>GS</sub> =-4.5V
Turn-off delay time	t <sub>d(off)</sub> *	-	350	-	ns	$R_L=1.3\Omega$
Fall time	t <sub>f</sub> *	-	170	-	ns	$R_G=10\Omega$
Total gate charge	Q <sub>g</sub> *	-	59	-	nC	I <sub>D</sub> =-9A,
Gate-source charge	Q <sub>gs</sub> *	-	11	-	nC	V <sub>GS</sub> =-4.5V
Gate-drain charge	Q <sub>gd</sub> *	-	9	-	nC	V <sub>DD</sub> ≒-6V

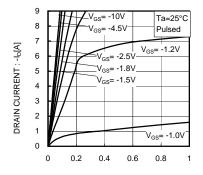
<sup>\*</sup>Pulsed

#### ●Body diode characteristics (Source-Drain) (Ta = 25°C)

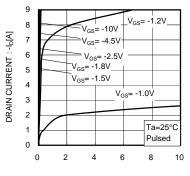
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	-1.2	V	$I_s=-9A$ , $V_{GS}=0V$

<sup>\*</sup>Pulsed

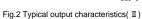
#### • Electrical characteristic curves

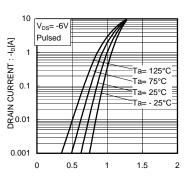


DRAIN-SOURCE VOLTAGE :  $-V_{DS}[V]$ Fig.1 Typical output characteristics( I)



DRAIN-SOURCE VOLTAGE :  $-V_{DS}[V]$ 





 $\mathsf{GATE}\text{-}\mathsf{SOURCE}\;\mathsf{VOLTAGE}: \text{-}\mathsf{V}_\mathsf{GS}[\mathsf{V}]$ 

Fig.3 Typical Transfer Characteristics

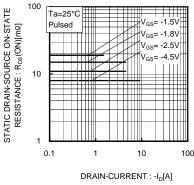


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

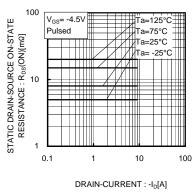


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

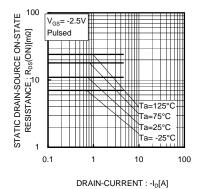


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(Ⅲ)

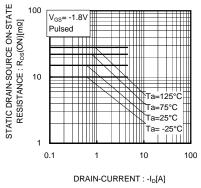


Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(IV)

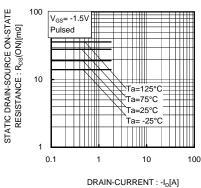


Fig.8 Static Drain-Source On-State
Resistance vs. Drain Current( V)

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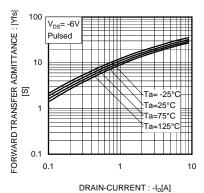
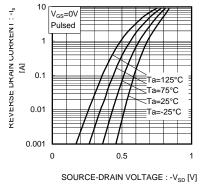


Fig.9 Forward Transfer Admittance vs. Drain Current



STATIC DRAIN-SOURCE ON-STATE

RESISTANCE:

R

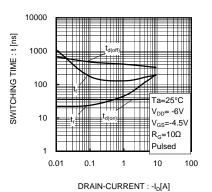


Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage

GATE-SOURCE VOLTAGE : -V<sub>GS</sub>[V]

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8

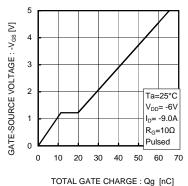
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Fig.11 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

Ta=25°C

Pulsed

Fig.12 Switching Characteristics



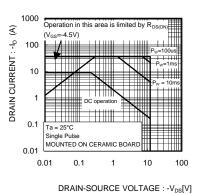


Fig.13 Dynamic Input Characteristics

Fig.14 Typical Capacitance vs. Drain-Source Voltage

Fig.15 Maximum Safe Operating Aera

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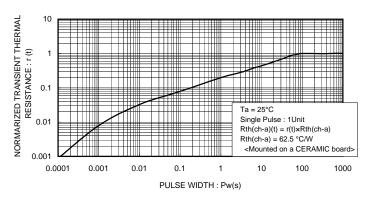


Fig.16 Normalized Transient Thermal Resistance vs. Pulse Width

#### Measurement circuits

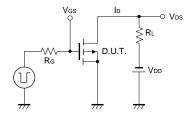


Fig.1-1 Switching Time Measurement Circuit

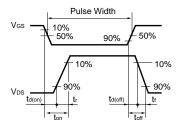


Fig.1-2 Switching Waveforms

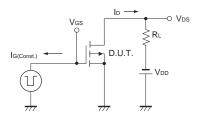


Fig.2-1 Gate charge measurement circuit

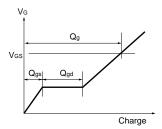


Fig.2-2 Gate Charge Waveform

#### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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